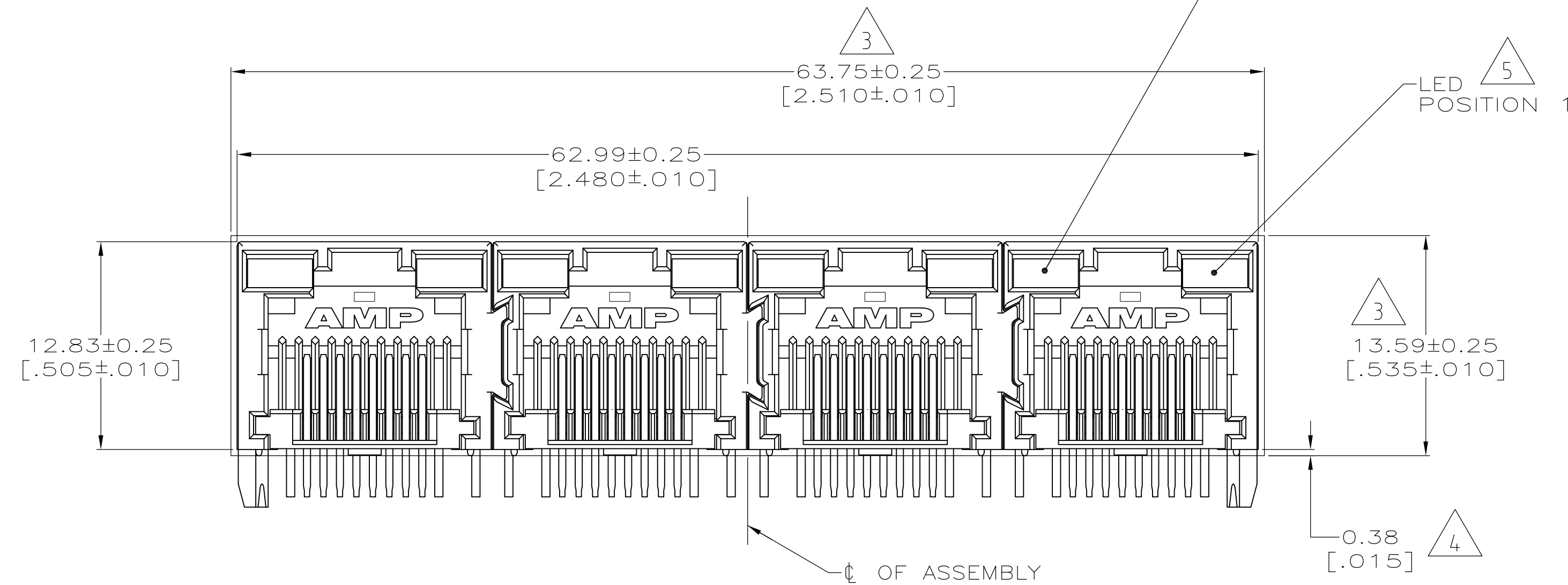
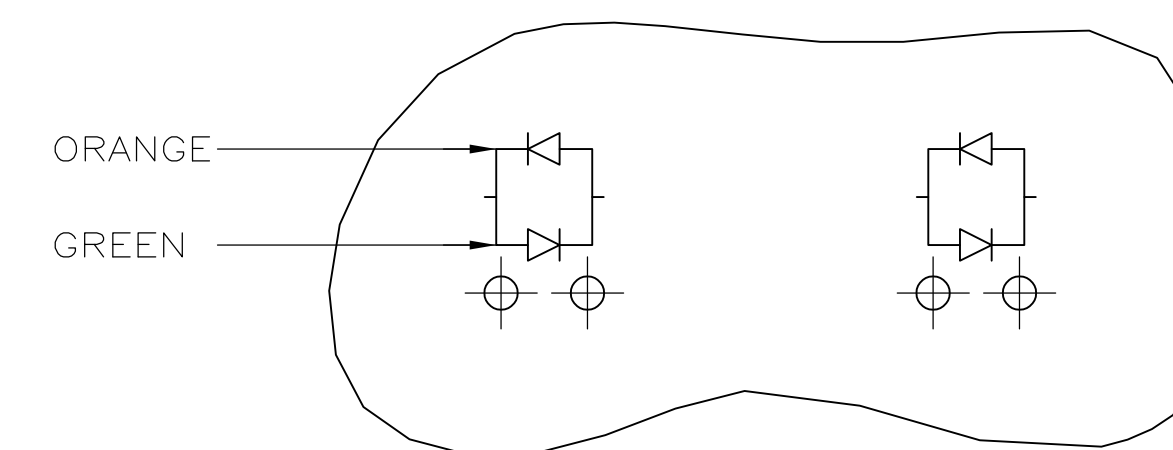




1. MATERIAL:
HOUSING — HIGH TEMPERATURE THERMOPLASTIC,
BLACK, UL94V-0.
TERMINALS — .36[.014] THICK PHOS BRONZE
PLATED WITH 3.81µm[.000150] MIN THICK
BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm
[.000050] MINIMUM GOLD IN LOCALIZED PLATE
AREA. ENTIRE TERMINAL PLATED WITH 1.27µm
[.000050] MINIMUM THICK NICKEL.
LIGHT EMITTING DIODE (LED) — DIFFUSED EPOXY
LENS, .51 x .51[.020 x .020] CARBON STEEL
WIREFRAME LEADS PLATED WITH 8.89µm[.000350]
TIN/COPPER OVER 2.03µm[.000080] SILVER
OVER 1.02µm[.000040] NICKEL UNDERPLATE
OVER 2.03µm[.000080] COPPER UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND
REGULATIONS PART 68, SUBPART F.
3. SUGGESTED PANEL OPENING DIMENSIONS.
4. SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR
AND BOTTOM PANEL OPENING.
5. SEE TABLE FOR COLOR OF LEDS AND NUMBER
REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT
IR REFLOW SOLDERING PROCESS COMPATIBLE.
7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



LED CURRENT DIAGRAM
406536-7 ONLY

A	ORANGE/GREEN	ORANGE/GREEN	406536-7
	YELLOW	YELLOW	406536-6
	GREEN	GREEN	406536-5
A	ORANGE/GREEN	YELLOW	406536-4
	YELLOW		406536-3
A	ORANGE/GREEN	GREEN	406536-2
	YELLOW	GREEN	406536-1
	POSITION 2	POSITION 1	
	INDICATOR COLOR FOR EACH HOUSING		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIM T. SPRINKLE 20SEP97 CHK T. SPRINKLE 20SEP97		 Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: TOLERANCES UNLESS OTHERWISE SPECIFIED: mm [INCHES]		AP'D M. DERSTINE 20SEP97 PRODUCT SPEC 108-1163-4 APPLICATION SPEC 114-2154		NAME INVERTED MODULAR JACK ASSEMBLY, 1X4, LED _ _	
		WEIGHT _		SIZE CAGE CODE DRAWING NO A1 00779 C=406536	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		RESTRICTED TO _	
CUSTOMER DRAWING SCALE 4:1 SHEET 1 of 1 REV C					